

AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application:

Listing of Claims

1. (currently amended) [[A]] The wiring-connecting material according to claim 15, comprising from 2 to 75 parts by weight of [[a]] the polyurethane resin, from 30 to 60 parts by weight of [[a]] the radical-polymerizable substance and from 0.1 to 30 parts by weight of [[a]] the curing agent generating a free radical upon heating.
2. (original) The wiring-connecting material according to claim 1, which further comprises from 0 to 40 parts by weight of a film-forming material.
3. (original) The wiring-connecting material according to claim 2, wherein said film-forming material is a polyimide resin.
4. (currently amended) The wiring-connecting material according to any one of claims 1 to 3 and 15, which further comprises conductive particles.
5. (currently amended) The wiring-connecting material according to any one of claims 1 to 3 and 15, wherein said polyurethane resin has a flow point of from 40°C to 140°C as measured by the flow tester method.

6. (currently amended) The wiring-connecting material according to any one of claims 1 to 3 and 15, wherein said curing agent has a weight retention at 25°C for 24 hours, of not less than 20% by weight.

7. (currently amended) The wiring-connecting material according to any one of claims 1 to 3 and 15, wherein said radical-polymerizable substance is urethane acrylate.

8. (currently amended) A process for producing a wiring-connected board[[;]], the process comprising a connecting step of interconnecting wiring members each having a connecting terminal, which members are so interconnected that their connecting terminals are able to make conduction between them;

 said connecting step comprising the step of heating the wiring-connecting material according to any one of claims 1 to [[7]] 3 and 15 while applying a pressure thereto via the wiring members; the wiring-connecting material being held between at least two wiring members so disposed that their sides having the connecting terminals face to each other.

9. (original) The process for producing a wiring-connected board according to claim 8, wherein at least one of the connecting terminals has a surface formed of at least one metal selected from gold, silver and a platinum group metal.

10. (previously presented) The wiring-connecting material according to claim 4, wherein said curing agent has a weight retention at 25°C for 24 hours, of not less than 20% by weight.

11. (previously presented) The wiring-connecting material according to claim 5, wherein said curing agent has a weight retention at 25°C for 24 hours, of not less than 20% by weight.

12. (previously presented) The wiring-connecting material according to claim 4, wherein said radical-polymerizable substance is urethane acrylate.

13. (previously presented) The wiring-connecting material according to claim 5, wherein said radical-polymerizable substance is urethane acrylate.

14. (previously presented) The wiring-connecting material according to claim 6, wherein said radical-polymerizable substance is urethane acrylate.

15. (new) A wiring-connecting material comprising a polyurethane resin, a radical-polymerizable substance and a curing agent generating a free radical upon heating, said wiring-connecting material having a flow property value, (B)/(A), of from 1.3 to 3.0, with (A) being an area at an initial stage and (B) being an area after heating and pressing when, using glass sheets of 0.7 mm thick and 15 mm X 15 mm, a wiring-connecting material of 35 µm thick and 5 mm X 5 mm is held between the glass sheets

and heated and pressured at 160°C and 2 MPa for 10 seconds.

16. (new) The wiring-connecting material according to claim 15, wherein said flow property value is in a range of from 1.5 to 2.5.

17. (new) The wiring-connecting material according to claim 15, having a temperature at which exothermic reaction rises, T_a , within a range of 70°C to 110°C, having a peak temperature (T_p) of $T_a + (5^\circ \text{ to } 30^\circ\text{C})$, and having an end temperature (T_e) of at most 160°C.

18. (new) The wiring-connecting material according to claim 15, having a storage elastic modulus at 25°C after curing, of from 100 to 2,000 MPa.

19. (new) The wiring-connecting material according to claim 15, wherein the radical-polymerizable substance is at least one selected from the group consisting of acrylates, methacrylates and maleimide compounds.

20. (new) The wiring-connecting material according to claim 15, wherein said polyurethane resin is obtained by reaction of a diol with a diisocyanate.

21. (new) The wiring-connecting material according to claim 15, wherein said polyurethane resin has a weight-average molecular weight in a range from 10,000 to 1,000,000.